BROADCOM

PCN-CCX-001204

Product Change Notice

Issue Date: December 07, 2018

Change Type:

Add Assembly Production Site – SPIL TAIWAN

Parts Affected:

BCM88034B1KFSBG
BCM88038B1KFSBG

Description and Extent of Change:

Add SPIL Taiwan as an additional assembly supplier for the above devices. We expect the change to be a drop in replacement. SPIL Taiwan is in mass production for the above package technology.

Reasons for Change:

Additional Assembly capacity

Effect of Change on Fit, Form, Function, Quality, or Reliability:

The device specification will remain the same, which will ensure product electrical performance remains the same. Appropriate electrical characterization and reliability qualification will be performed on representative products to ensure normal parametric distribution, consistent electrical performance, and reliability.

Effective Date of Change:

Product shipments using this change will begin after March 10, 2019. Timing of shipment of the changed part will vary by part number depending on qualification completion, customer demand, and inventory levels.

Qualification Data:

Package Qualification Reference: PQ03429
Fab Technology: 28nm
Package Type: FCBGA+HS
Package Size: 55x55mm
Lead Count: 2870
Bump Composition: Ultra Low Alpha (<0.0020cph/cm2) 63Sn/37Pb

Stress Test	Condition	Read points Cycles / Hrs.	Sample Size	Requirements	Results (# fail/ss)
Precondition	MSL4 JESD22-A113E		260 units	0 failures	0 / 260
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	300 cycles	76 units	0 failures	0 / 76
uHast	130°C/85%RH/ JEDEC Std. 22-A102-C	96hrs	77 units	0 failures	0 / 77
HTSL	TA=150°C JEDEC Std. 22-A103-C	1000hrs	77 units	0 failures	0 / 77

Please contact your Broadcom Inc. field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.